## IN THE CLAIMS

Please amend the claims as follows.

1. (Currently Amended) An apparatus for socketing and testing integrated circuits comprising:

an air machine that is operable to controllably provide a thermally-varying air flow; and a housing comprising (i) a printed circuit board that is operable to receive a device under test, the printed circuit board comprising a leadless socket, and (ii) a controller that is operable to control testing of the received device under test;

wherein said air machine is associable with said housing to form an at least substantially air-tight chamber ensconcing the received device under test.

- 2. (Original) The apparatus as set forth in Claim 1 wherein said housing further comprises a power supply.
- 3. (Original) The apparatus as set forth in Claim 1 wherein said printed circuit board is circular shaped.
- 4. (Previously Presented) The apparatus as set forth in Claim 3 wherein said housing further comprises input/output (I/O) connectors that are placed circumferentially and symmetrically near the edge of the printed circuit board.

2

- 5. (Currently Amended) The apparatus as set forth in Claim 3 wherein said printed circuit board comprises a the leadless socket is self-registering.
- 6. (Currently Amended) The apparatus as set forth in Claim 5 wherein said leadless socket is operable to receive the device under test in [[the]] <u>a</u> center of the [[P]] <u>printed</u> circuit board.
- 7. (Currently Amended) A method of operating an apparatus for socketing and testing integrated circuits, said apparatus comprising an air machine and a housing, said housing comprising a printed circuit board and a controller, said method comprising the steps of:
- (i) receiving a device under test at the printed circuit board, the printed circuit board comprising a leadless socket, and
- (ii) associating said air machine with said housing to form an at least substantially airtight chamber ensconcing the received device under test, the air machine operable to controllably provide a thermally-varying air flow.
- 8. (Original) The method as set forth in Claim 7 wherein said housing further comprises a power supply, and said method comprising the step of powering on the apparatus.

DOCKET NO. P05085 SERIAL NO. 10/075,832 PATENT

- 9. (Original) The method as set forth in Claim 7 wherein said printed circuit board is circular shaped, and said method comprising the step of controlling testing of the received device under test with said controller.
- 10. (Previously Presented) The method as set forth in Claim 9 wherein said housing further comprises input/output (I/O) connectors that are placed circumferentially and symmetrically near the edge of the printed circuit board.
- 11. (Currently Amended) The method as set forth in Claim 9 wherein said printed circuit board comprises a the leadless socket is self-registering.
- 12. (Currently Amended) The method as set forth in Claim 11 wherein said leadless socket is operable to receive the device under test in [[the]] <u>a</u> center of the [[P]] <u>printed</u> circuit board.

13. (Currently Amended) An apparatus for socketing and testing integrated circuits comprising:

an air machine that is operable to controllably provide a thermally-varying air flow; and a housing comprising (i) a universal printed circuit board that is operable to receive a device under test, the printed circuit board comprising a leadless socket, (ii) a controller that is operable to control testing of the received device under test, and (iii) a power supply;

wherein said air machine is associable with said housing to form an at least substantially air-tight chamber ensconcing the received device under test.

- 14. (Original) The apparatus as set forth in Claim 13 wherein said power supply is a battery.
- 15. (Original) The apparatus as set forth in Claim 13 wherein said universal printed circuit board is circular shaped.
- 16. (Previously Presented) The apparatus as set forth in Claim 15 wherein said housing further comprises input/output (I/O) connectors that are placed circumferentially and symmetrically near the edge of the universal printed circuit board.

## 17. (Cancelled).

DOCKET NO. P05085 SERIAL NO. 10/075,832 PATENT

- 18. (Currently Amended) The apparatus as set forth in Claim [[17]] 13 wherein said leadless socket is operable to receive the device under test in [[the]] a center of the printed circuit board.
- 19. (Previously Presented) The apparatus as set forth in Claim 13 wherein the device under test is one of a radio frequency (RF) integrated circuit and a high-frequency integrated circuit.
- 20. (Currently Amended) The apparatus as set forth in Claim [[17]] 13 wherein said leadless socket is self-registering.
- 21. (New) The method of Claim 7, further comprising setting one or more desired temperatures and one or more desired cycle times for a test of the integrated circuits.